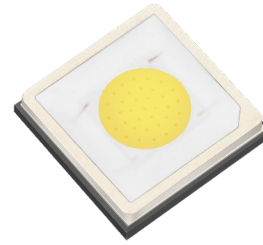


SFT-25R-WES

High Power White LEDs



Features

With Luminus' advanced chip and packaging technologies, SFT-25R-W maximizes the Candela/Lumen K-Factor for high optical performance in directional lighting:

- A small emitter enables high intensity, long beam distance and small optics.
- A patented round emitter, in comparison with a square emitter, enables better uniformity and higher intensity in beam spots.
- A flat window, in comparison with a domed cover, allows the optics to be closer to the emitter to achieve higher intensity and longer beam distance.

In addition, Luminus phosphor-on-chip technology's high uniformity of color over radiation angle enables superior beam spot light quality.

- Maximum Drive Current: Target 7.5 A
- Color Temperature: 5000K, 5700K, 6500K
- Color Rendering Index: Typ. 73 (5000K, 5700K), Typ.70 (6500K)
- Low thermal resistance: 0.7 - 1.1°C/W
- ANSI-compatible chromaticity bins
- Electrically isolated thermal path
- 8 kV HBM ESD rating per ANSI/ESDA/JEDEC JS-001

Applications

- Portable Lights
- Bicycle Lights
- Transportation Lighting
- LED Work Lights
- Outdoor and Roadway Lighting
- Industrial Lighting

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Ordering Information

Ordering Part Numbers¹

CRI	CCT	Luminous Flux		Ordering Part Number
		Minimum Flux Bin ¹	Minimum Flux $I_f=1500 \text{ mA}, T_j=85^\circ\text{C}$	
>70	5000K	F6	550 lm	SFT-25R-WE50-A2-ENG
>70	5700K	F6	550 lm	SFT-25R-WE57-A2-ENG
>65	6500K	F8	610 lm	SFT-25R-WS65-A2-ENG

Part Number Nomenclature

SFT	25R	W<xyy>	<p#>	ENG
Product Family	Chip Area	Color	Package Configuration	Bin Kit
S: Surface Mount F: Flat Window T: Single Emitter	25: 2.5 mm ² R: Round Shape	W: White <x> CRI Category Code E: CRI>70 S: CRI>65 <yy> Color Temperature 50: 5000K 65: 6500K	<p> Solder Pad Configuration A: type A - see page 10 <#> Chip Generation 1: Gen 1 2: Gen 2	ENG: Pre-Production Parts

Note:

1. The Ordering Part Number specifies the Minimum Flux Bin in shipment; higher flux bins may be shipped without advance notice. Please refer to 'Luminous Flux Binning' table for details of all flux bins.



Binning Structure

Luminous Flux Binning^{1,2}

Flux Bin Code	Binning @ 1500 mA			Correlated Minimum Flux (lm) @ $T_j=85^\circ\text{C}^2$				
	$T_j=85^\circ\text{C}^1$		$T_j=25^\circ\text{C}^1$	700 mA	2000 mA	3000 mA	5000 mA	7500 mA
	Minimum Flux (lm)	Maximum Flux (lm)	Minimum Flux (lm)					
F6	550	580	616	281	699	952	1353	1683
F7	580	610	650	296	737	1003	1427	1775
F8	610	640	683	311	775	1055	1501	1867
F9	640	680	717	326	813	1107	1574	1958
G1	680	720	762	347	864	1176	1673	2081

Forward Voltage Binning³

Voltage Bin Code	Binning @ 1500 mA, $T_j = 85^\circ\text{C}$	
	Minimum Voltage (V)	Maximum Voltage (V)
VJ	2.7	2.9
VK	2.9	3.1
VL	3.1	3.3

Note:

- LEDs are measured at 25°C ambient temperature with 1500 mA 20 ms single pulse. The measured values are correlated to values at 85°C junction temperature (T_j). Luminus maintains a $\pm 6\%$ tolerance on flux measurement.
- Flux values at other junction temperature (T_j) and/or forward current conditions are calculated and for reference only.
- Individual bins are not orderable.



Binning Structure

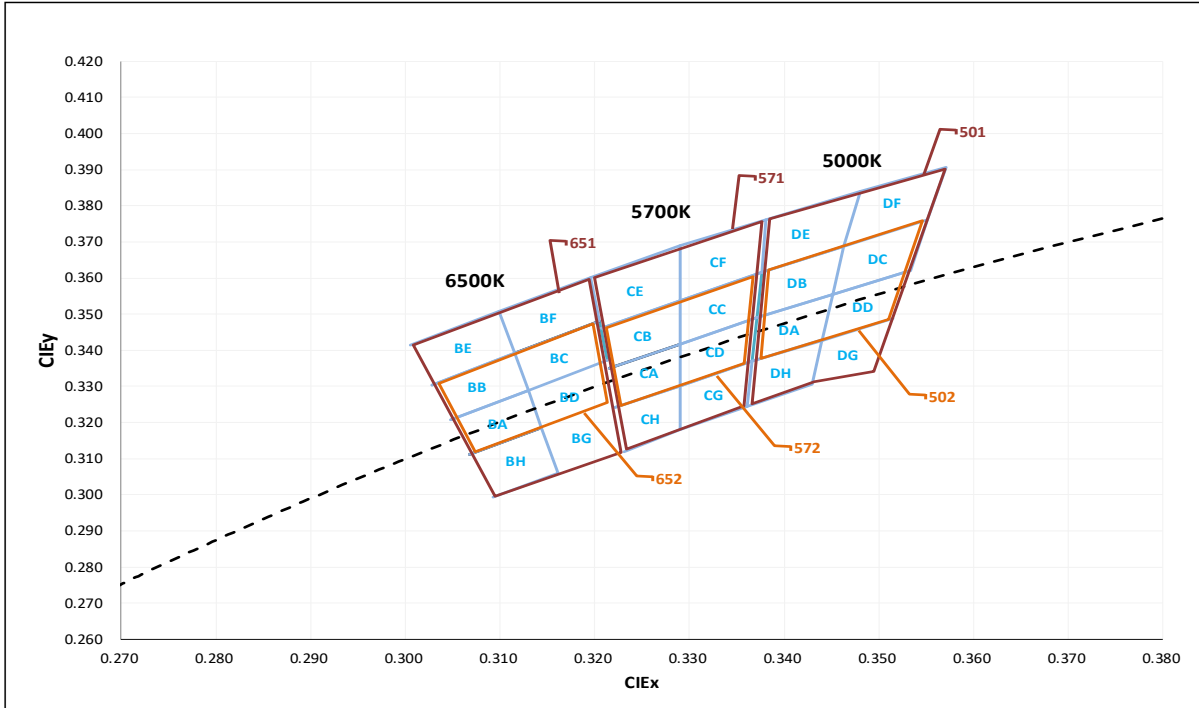
Chromaticity Binning Coordinates

CCT	Bin Code	CIE _x	CIE _y	Bin Code	CIE _x	CIE _y	Bin Code	CIE _x	CIE _y	Bin Code	CIE _x	CIE _y
5000K	DA	0.3371	0.3490	DB	0.3376	0.3616	DC	0.3463	0.3687	DD	0.3451	0.3554
		0.3451	0.3554		0.3463	0.3687		0.3551	0.3760		0.3533	0.3620
		0.3440	0.3427		0.3451	0.3554		0.3533	0.3620		0.3515	0.3487
		0.3366	0.3369		0.3371	0.3490		0.3451	0.3554		0.3440	0.3427
	DH	0.3366	0.3369	DE	0.3381	0.3762	DF	0.3480	0.3840	DG	0.3440	0.3428
		0.3440	0.3428		0.3480	0.3840		0.3571	0.3907		0.3515	0.3487
		0.3429	0.3307		0.3463	0.3687		0.3551	0.3760		0.3495	0.3339
		0.3361	0.3245		0.3376	0.3616		0.3463	0.3687		0.3429	0.3307
5700K	CA	0.3215	0.3350	CB	0.3207	0.3462	CC	0.3290	0.3538	CD	0.3290	0.3417
		0.3290	0.3417		0.3290	0.3538		0.3376	0.3616		0.3371	0.3490
		0.3290	0.3300		0.3290	0.3417		0.3371	0.3490		0.3366	0.3369
		0.3222	0.3243		0.3215	0.3350		0.3290	0.3417		0.3290	0.3300
	CH	0.3222	0.3243	CE	0.3196	0.3602	CF	0.3290	0.3690	CG	0.3290	0.3300
		0.3290	0.3300		0.3290	0.3690		0.3381	0.3762		0.3366	0.3369
		0.3290	0.3180		0.3290	0.3538		0.3376	0.3616		0.3361	0.3245
		0.3231	0.3120		0.3207	0.3462		0.3290	0.3538		0.3290	0.3180
6500K	BA	0.3048	0.3207	BB	0.3028	0.3304	BC	0.3115	0.3391	BD	0.3130	0.3290
		0.3130	0.3290		0.3115	0.3391		0.3205	0.3481		0.3213	0.3373
		0.3144	0.3186		0.3130	0.3290		0.3213	0.3373		0.3221	0.3261
		0.3068	0.3113		0.3048	0.3207		0.3130	0.3290		0.3144	0.3186
	BH	0.3068	0.3113	BE	0.3005	0.3415	BF	0.3099	0.3509	BG	0.3144	0.3186
		0.3144	0.3186		0.3099	0.3509		0.3196	0.3602		0.3221	0.3261
		0.3161	0.3059		0.3115	0.3391		0.3205	0.3481		0.3231	0.3120
		0.3093	0.2993		0.3028	0.3304		0.3115	0.3391		0.3161	0.3059



Binning Structure

Chromaticity Binning Diagram^{1,2}



Chromaticity Bin Kit Codes

CCT	Bin Kit	Chromaticity Bins
5000K	501	DA, DB, DC, DD, DE, DF, DG, DH
	502	DA, DB, DC, DD
5700K	571	CA, CB, CC, CD, CE, CF, CG, CH
	572	CA, CB, CC, CD
6500K	651	BA, BB, BC, BD, BE, BF, BG, BH
	652	BA, BB, BC, BD

Note:

- LED chromaticity is measured and binned at 25°C ambient temperature with 1500 mA 20 ms single pulse.
- Luminus maintains a tolerance of ± 0.005 on Chromaticity (CIE_x, CIE_y) measurement.



Absolute Maximum Ratings

Parameter		Symbol	Value	Unit
DC Forward Current	Minimum	$I_{f\ min}$	0.1	A
	Maximum	$I_{f\ max}$	Target 7.5	
Surge Current ($t < 10$ ms, Duty Cycle < 10%)		I_s	9.0	A
Reverse Voltage ($I_r = 10$ mA)		V_r	5	V
Power Dissipation		P_D	Target 29	W
Junction Temperature		$T_{j\ max}$	150	°C
Operating Temperature		T_{opr}	-40 to 100	°C
Storage Temperature		T_{stg}	-40 to 100	°C
ESD withstand Voltage HBM Per ANSI/ESDA/JEDEC JS-001		V_{HBM}	8	kV
ESD withstand Voltage CDM Per ANSI/ESDA/JEDEC JS-002		V_{CDM}	1	kV

Product Characteristics

Parameter		Symbol	Value		Unit
			WS	WE	
Color Rendering Index ¹ ($T_j = 85^\circ\text{C}$)	Minimum	CRI_{\min}	65	70	
	Typical	CRI_{typ}	70	73	
Forward Voltage ($I_f = 1500$ mA, $T_j = 85^\circ\text{C}$)	Minimum	$V_{f\ \min}$	2.7		V
	Typical	$V_{f\ \text{typ}}$	3.0		
	Maximum	$V_{f\ \max}$	3.3		
Temperature Coefficient of Voltage		$\partial V_f / \partial T$	-1.4		mV/°C
Viewing Angle (FWHM)		$2\theta_{1/2}$	120°		
Thermal Resistance (Electrical) Junction/Solder Point		$R_{\text{thjs-EL}}$	0.7 - 1.1		°C/W

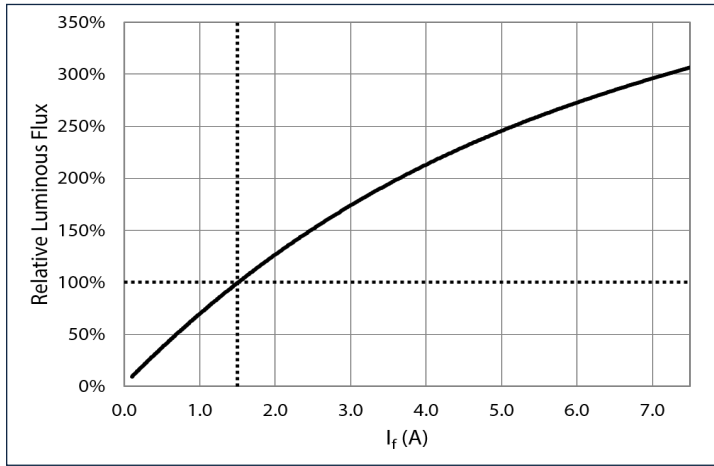
Note:

1. Luminus maintains a tolerance of ± 2 on Color Rendering Index (CRI) measurement.

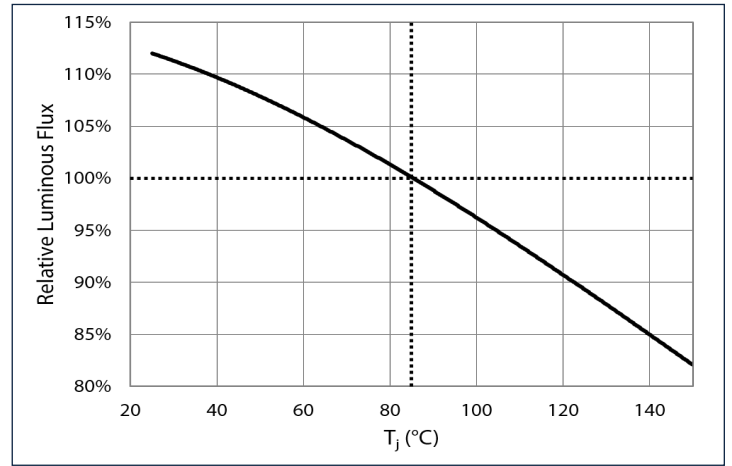


Relative Luminous Flux

Forward Current: $\phi_v/\phi_v(1500\text{ mA}), T_j = 85^\circ\text{C}$

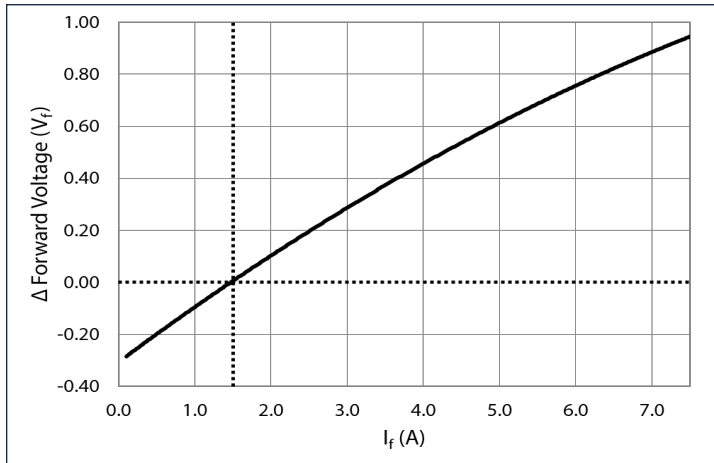


Temperature (T_j): $\phi_v/\phi_v(85^\circ\text{C}), I_f = 1500\text{ mA}$

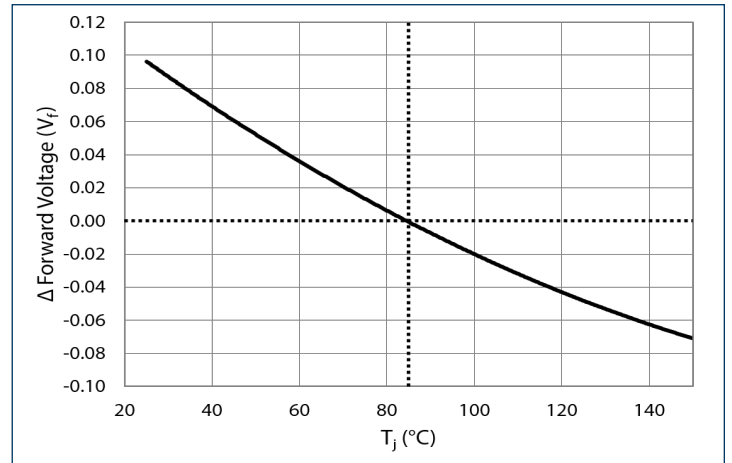


Forward Voltage

Forward Current: $\Delta V_f = V_f(I_f) - V_f(1500\text{ mA}), T_j = 85^\circ\text{C}$

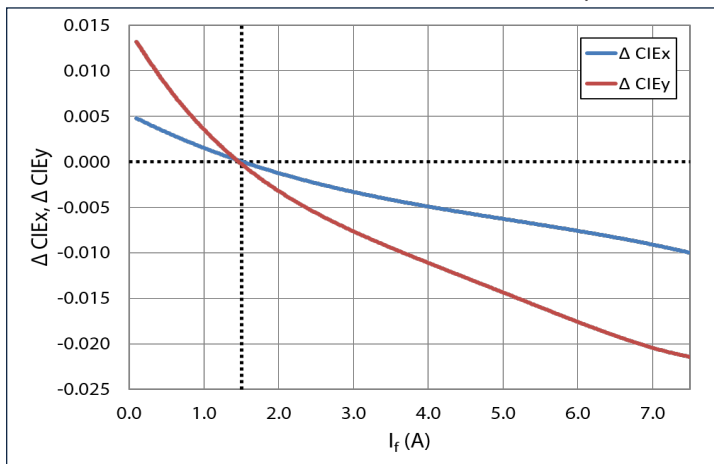


Temperature (T_j): $\Delta V_f = V(T_j) - V(85^\circ\text{C}), I_f = 1500\text{ mA}$

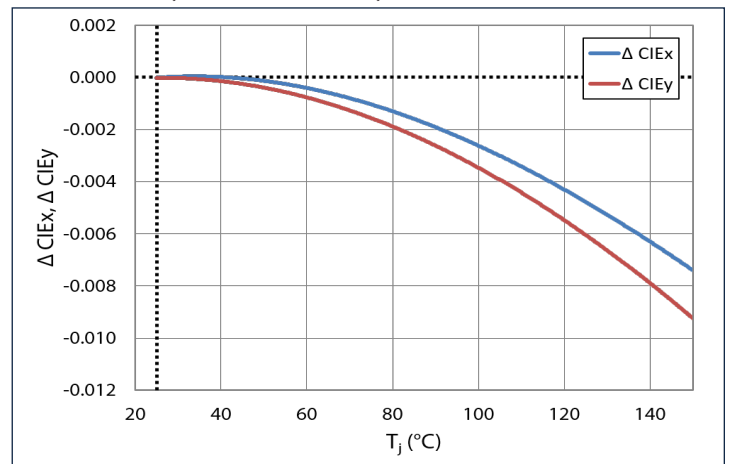


Relative Chromaticity

Forward Current: $\Delta \text{CIEx,y} = \text{CIEx,y}(I_f) - \text{CIEx,y}(1500\text{ mA}), T_j = 85^\circ\text{C}$



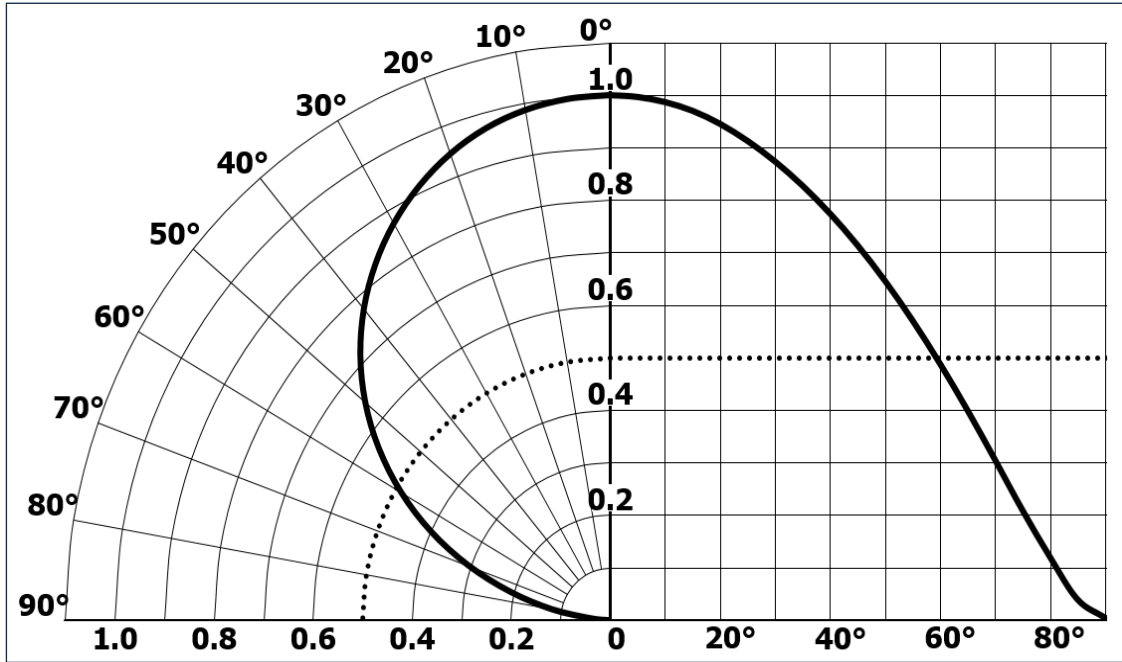
Temperature (T_j): $\Delta \text{CIEx,y} = \text{CIEx,y}(T_j) - \text{CIEx,y}(25^\circ\text{C}), I_f = 1500\text{ mA}$





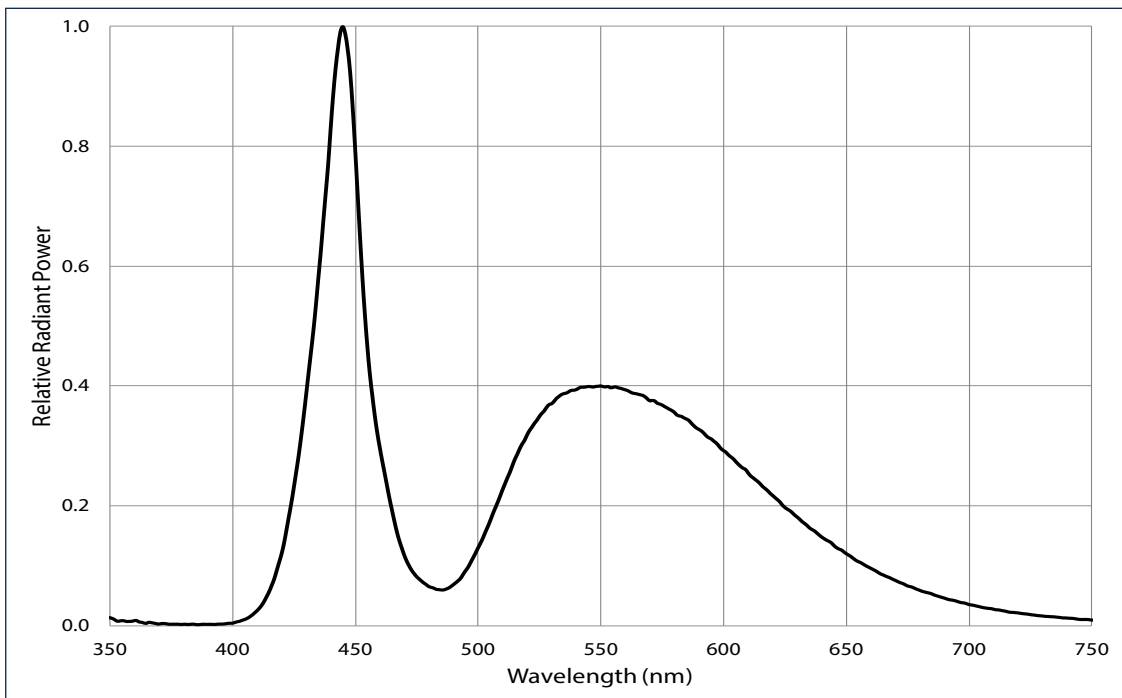
Angular Distribution

$I_f = 1500 \text{ mA}$; $T_j = 25^\circ\text{C}$



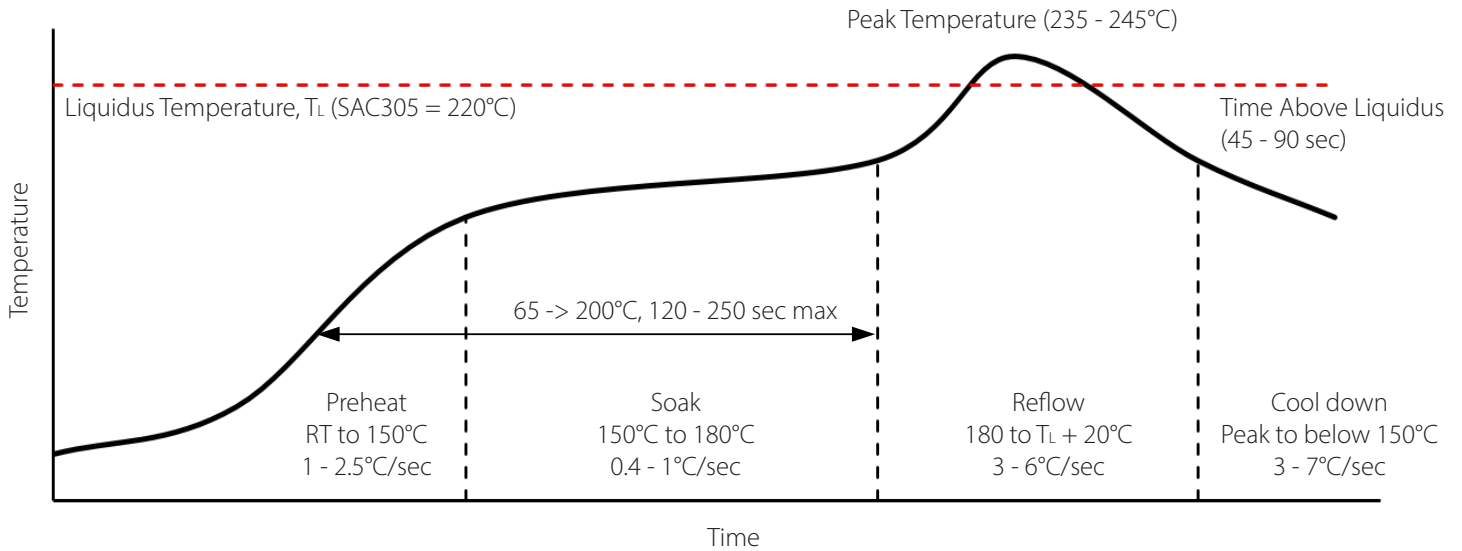
Relative Spectral Power Distribution

$I_f = 1500 \text{ mA}$; $T_j = 85^\circ\text{C}$





Soldering Profile



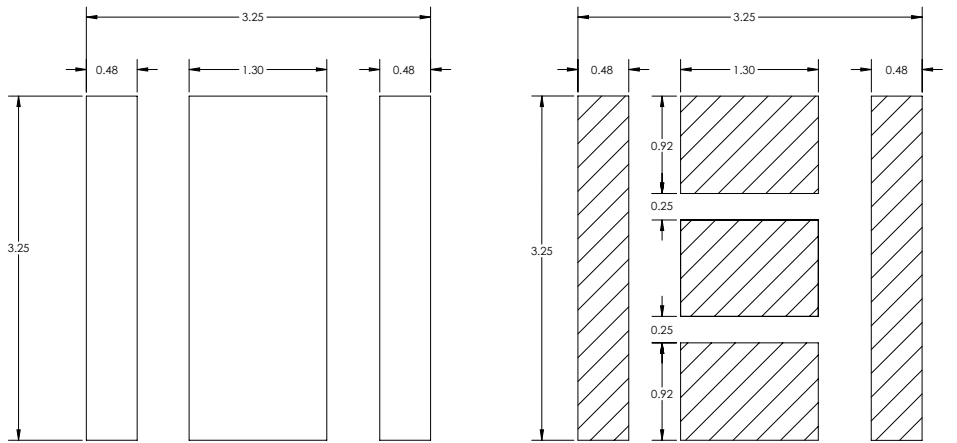
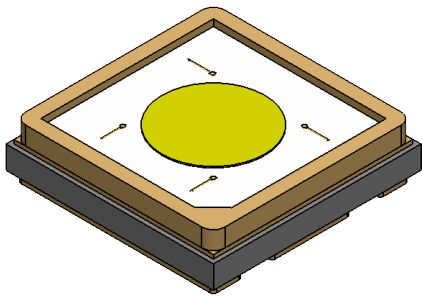
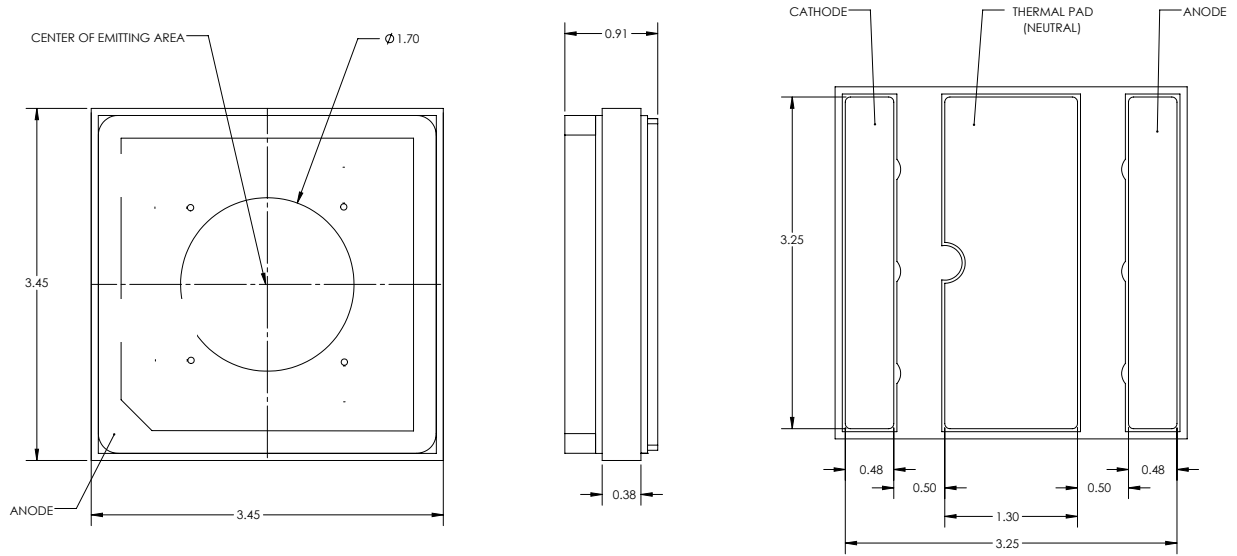
SMT Rework Guideline	Manual Hotplate Reflow	Hot Air Gun Reflow
Heating Time		< 60 sec
Hotplate Temperature	< 245°C	< 150°C

Note:

- Product complies to Moisture Sensitivity Level 3 (MSL 3).
- The numbers in the table are specific to SAC305. Luminus recommends using an SAC305 solder paste with a no-clean flux for RoHS compliant products.
- During the pick and place process, axial forces on the dome (or window) should not exceed 0.5 Newtons (N).
- Use of a multi-zone IR reflow oven with a nitrogen blanket is recommended.
- Time-temperature profile of the reflow process showing the four functional profile zones are defined in IPC-7801. Temperature is referenced to the center of the PCB.
- Luminus recommends to use the solder paste data sheet information as a starting point in time-temperature process development.
- These are general guidelines. Consult the solder paste manufacturer's datasheet for guidelines specific to the alloy and flux combination used in your application.
For more information, please refer to:
<https://luminusdevices.zendesk.com/hc/en-us/articles/360060306692-How-do-I-Reflow-Solder-Luminus-SMD-Components->
- For any technical questions about soldering process, please contact Luminus at techsupport@luminus.com.



Mechanical Dimensions¹



Recommended PCB Solder PAD

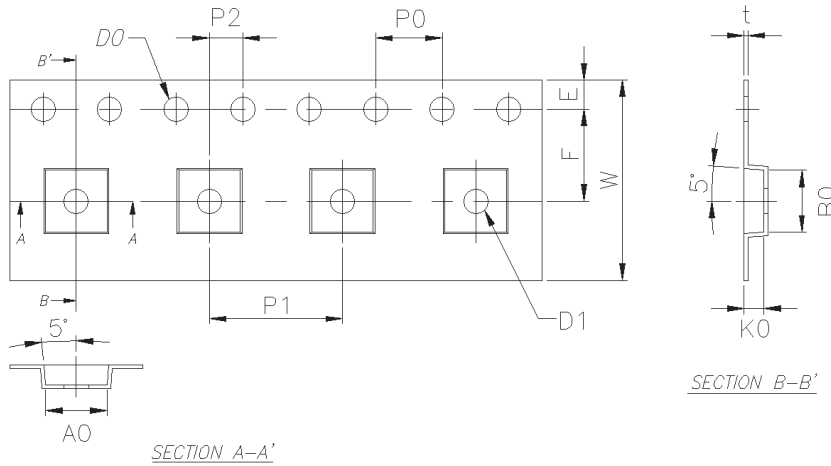
Recommended Stencil Pattern

Note:

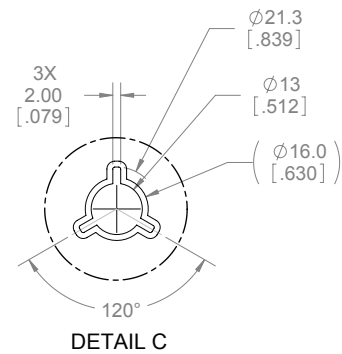
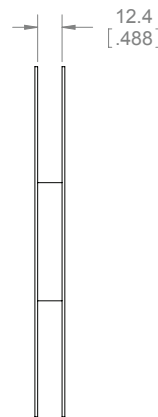
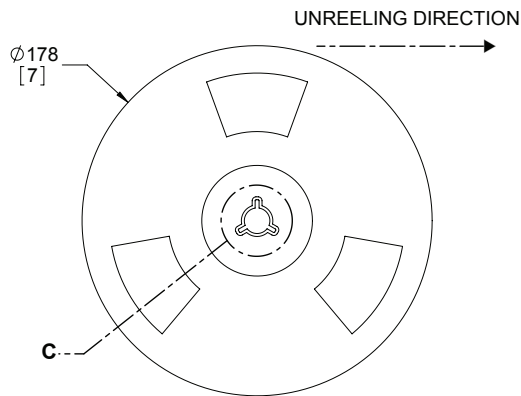
1. All dimensions are in millimeter ± 0.13 mm.



Tape and Reel Outline



Parameter	Dimension (mm)
A0	3.70±0.10
B0	3.70±0.10
D0	1.50+0.10
D1	1.50±0.10
E	1.75±0.10
F	5.50±0.10
K0	1.20±0.10
P0	4.00±0.10
P1	8.00±0.10
P2	2.00±0.10
t	0.23±0.05
W	12±0.3



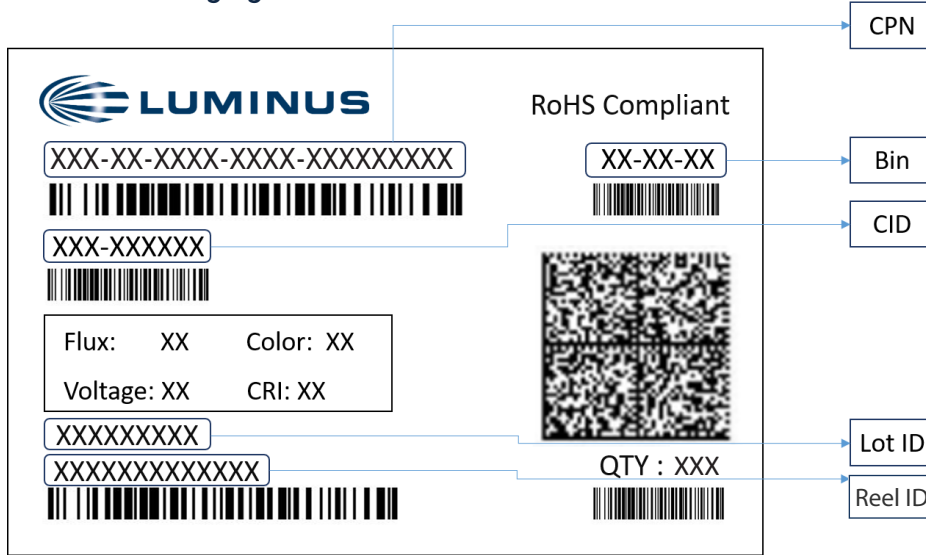
Note:

1. Each reel contains 500 units of LEDs.
2. Leave 240 mm of type empty for lead in (30 empty pockets).
3. Leave 1200 mm of type empty for trailer (150 empty pockets).
4. All dimensions must comply to EIA-481-D.
5. Final tape and reel packaging must meet the requirements of JEDEC-STD-033, LEVEL 2A.



Shipping Label

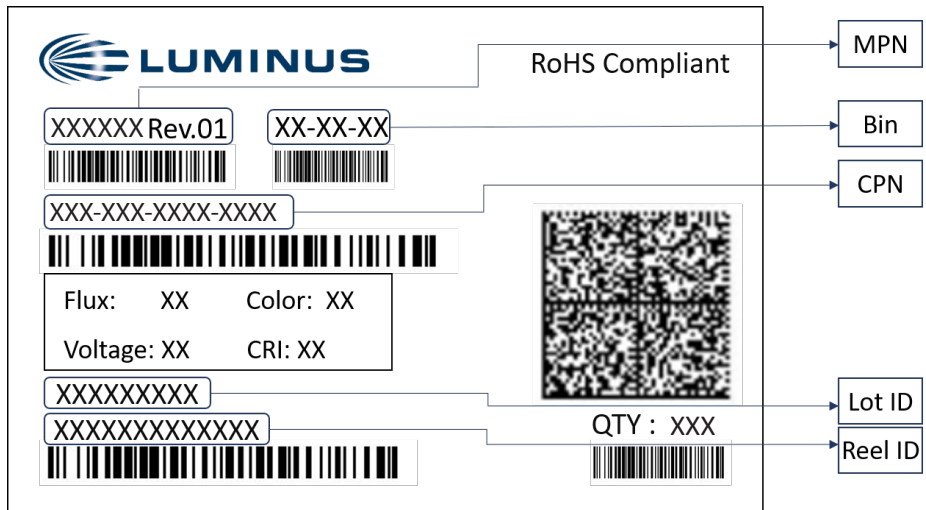
Label on Packaging Box



Label Fields:

- CPN:** Luminus ordering part number
- CID:** Customer's part number
- QTY:** Quantity of parts per reel
- Flux:** Bin as defined on page 3
- Voltage:** Bin as defined on page 3
- Color:** Bin as defined on page 4
- CRI:** NA
- Lot ID & Reel ID:** For Luminus internal use

Label on Reel



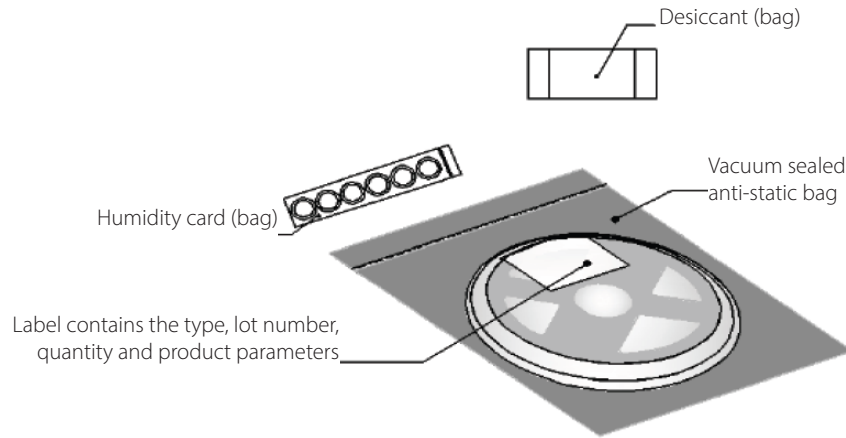
Label Fields:

- CPN:** Luminus ordering part number
- MPN:** For Luminus internal use
- QTY:** Quantity of parts per reel
- Flux:** Bin as defined on page 3
- Voltage:** Bin as defined on page 3
- Color:** Bin as defined on page 4
- CRI:** NA
- Lot ID & Reel ID:** For Luminus internal use



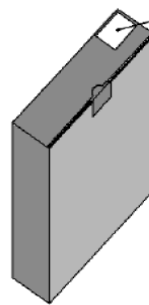
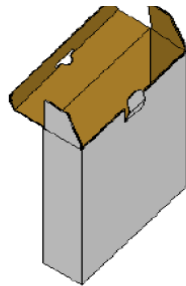
Packaging

Packaged Reel



Packaging boxes

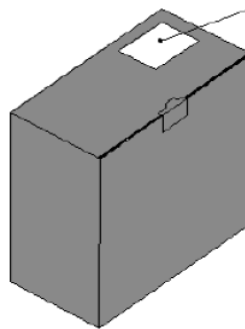
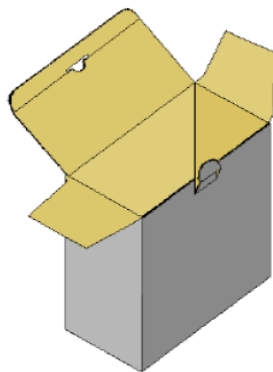
Box Size 1 - 5 reels per box
Size: 22.5 x 24.5 x 6.5 cm



Label contains the type, lot number, quantity and product parameters

*Capacity 5 reels per box

Box Size 2 - 10 reels per box
Size: 22.5 x 24.5 x 13 cm



Label contains the type, lot number, quantity and product parameters

*Capacity 10 reels per box

Packing Configuration:

- 500 units per reel
- Each reel is enclosed in anti-static bag
- Shipping label is placed on top of each reel
- Multiple labels are attached to the box (one label per reel inside the box)



Notes

Static Electricity

1. The products are sensitive to static electricity, and care should be taken when handling them.
2. Static electricity or surge voltage will damage the LEDs. It is recommended to wear anti-electrostatic gloves or wristband when handling the LEDs.
3. All devices, equipment and machinery must be properly grounded. It is recommended that measures be taken against surge voltage to the equipment that mounts the LEDs.

Reference: [APN-002815](#) Electrical Stress Damage to LEDs and How to Prevent It

Storage

1. Before opening the package

The LEDs should be kept at a temperature lower than 40°C and relative humidity lower than 90%. The LEDs should be used within a year. When storing the LEDs, moisture proof package with absorbent material (silica gel) is recommended.

2. After opening the package

The LEDs should be kept at a temperature lower than 30°C and relative humidity lower than 60%. The LEDs should be soldered within 168 hours (7 days) after opening the moisture proof package.

If unused LEDs remain, they should be stored in moisture proof packages, such as sealed containers with moisture absorbent material (silica gel). It is also recommended to return the unused LEDs to the original moisture proof package and to seal it again.

If the moisture absorbent material (silica gel) vaporizes or passes the expiration date, baking treatment should be performed by using the following conditions : 60°C for 20 hours.

The LED's electrode and lead frame comprise a silver plated copper alloy. The silver surface may be affected by environments. Please avoid conditions which may cause the LEDs to corrode or discolor. The corrosion or discoloration might lower solderability or affect optical characteristics.

Please avoid rapid transition in ambient temperature, especially in high humidity environments where condensation can occur.